

IN THE CLAIMS:

The following is a complete listing of claims in this application.

1. (currently amended) A light emitting diode device comprising:
a circuit substrate;
a lower reflection film provided on an upper surface of the circuit substrate;
an LED mounted on the upper surface of the circuit substrate;
a resin layer encapsulating the LED and the lower reflection film;

an upper reflection layer provided on an upper surface of the resin layer,

the upper reflection layer formed by a metal being disposed opposite the LED, and being ~~constructed and arranged~~ formed into a thin film to transmit a portion of light rays emitted by the LED through the upper reflection layer in a forward direction and to reflect another portion of the light rays emitted by the LED,

wherein the light rays reflected by the upper reflection layer are further reflected by the lower reflection film on the circuit substrate, and the light rays reflected by the lower reflection film are discharged in the forward direction passing through the upper reflection layer and through side walls of the resin layer to be diffused.

Claims 2-3 (canceled).

4. (previously presented) The device according to claim 1 wherein the upper reflection layer comprises a transparent holding plate and an upper reflection film provided between the upper surface of the resin layer and the underside of the holding plate.

5. (original) The device according to claim 4 wherein the

upper reflection film is formed by a metal plating.

6. (original) The device according to claim 4 wherein the upper reflection film has an area smaller than an area of the resin layer.